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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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AT25DF021A



2-Mbit, 1.7V-3.6V Minimum SPI Serial Flash Memory

DATASHEET (ADDENDUM)

High Temperature Operation (125°C)

This data sheet addendum is to be used in conjunction with the existing AT25DF021A datasheet specifications. The Adesto AT25DF021A 2Mbit Serial Flash devices will operate @ 125°C with the following datasheet caveats. All other parameters will meet the existing datasheet specifications.

The ordering code suffix (CAN# Code) 'HR' or 'HT' must be used to ensure correct operation at this extended temperature range. Adesto will not modify and republish the current datasheet to reflect the CAN# ordering code or the above caveats. The standard AT25DF021A datasheet is available at http://www.adestotech.com.

1. Electrical Specifications

1.1 DC and AC Operating Range

	AT25DF021A-xxxH	R
Operating Temperature	-40°C to +125°C	
Endurance (Maximum)	20,000 Cycles	

1.2 DC, AC, Program and Erase Characteristics

		1.7V to 3.6V		2.3V to 3.6V				
Symbol	Parameter	Min	Тур	Max	Min	Тур	Max	Units
I _{UDPD}	Ultra Deep Power-Down Current		.2	1		.3	1	μΑ
I _{DPD}	Deep Power-Down Current		5	40		8	40	μΑ
I _{SB}	Standby Current		25	65		25	65	μΑ
I _{CC3} (1)(2)	Active Current, Program Operation		11	14.5		12	14.5	mA
I _{CC4} ^{(1) (2)}	Active Current, Erase Operation		11	14.5		12	14.5	mA
f _{SCK}	Maximum Clock Frequency for All Operation (including 0Bh Opcode)			85			85	MHz
f _{RDLF}	Maximum Clock Frequency for 03h			25			25	MHz
f _{RDDO}	Maximum Clock Frequency for 3Bh Opcode			40			40	MHz
t _{PP}	Page Program Time (256 Bytes)		2	6		2	5	ms
t _{PE}	Page Erase Time		6	20		6	20	ms
t _{BP}	Byte Program Time		12			12		μs
	Block Erase Time (4K)		45	100		45	100	ms
t _{BLKE}	Block Erase Time (32K)		300	700		300	700	ms
	Block Erase Time (64K)		500	1400		500	1400	ms
t _{CHPE}	Chip Erase Time		2.5	6		2.5	6	s

- 1. Typical values measured at 1.8V @ 25°C for the 1.7V to 3.6V range.
- 2. Typical values measured at 3.0V @ 25°C for the 2.3V to 3.6V range.

2. Ordering Code

2.1 Green Package Options (Pb/Halide-free/RoHS Compliant)

Ordering Code ⁽¹⁾	Package	Operating Voltage	Max. Freq. (MHz)	Operation Range		
AT25DF021A-SSHNHR-T	8S1					
AT25DF021A-SSHNHR-B	001					
AT25DF021A-XMHNHR-T	8X 8MA1					
AT25DF021A-XMHNHR-B		1.7V to 3.6V	85MHz	Extended		
AT25DF021A-MHNHR-T		ΟΝΛΛ1		1.7 V to 3.0 V	OSIVII 12	(-40°C to +125°C)
AT25DF021A-MHNHR-Y		OWAT				
AT25DF021A-MAHNHR-T	8MA3					
AT25DF021A-DWFHT (2)	DWF					

- 1. The shipping carrier option code is not marked on the devices.
- 2. Contact Adesto for mechanical drawing or Die Sales information.

Package Type			
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline Package (JEDEC SOIC)		
8X	8-lead, Thin Shrink Small Outline Package		
8MA1	8-pad, 5 x 6 x 0.6mm, Thermally Enhanced Plastic Ultra Thin Dual Flat No-lead (UDFN)		
8MA3	8-pad, 2 x 3 x 0.6mm, Thermally Enhanced Plastic Ultra Thin Dual Flat No Lead Package (UDFN)		
DWF	Die in Wafer Form		

3. Revision History

Revision Level – Release Date	History
A – January 2015	Initial release.
B – May 2015	Updated AC and DC Characteristics.
C - May 2015	Added tray option to 5x6 UDFN.
D – November 2015	Removed preliminary package note.



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